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Polymer PTC Devices

CYG Wayon Circuit Protection Co., Ltd.

No.1001, Shiwan Qi Road, Shanghai 201207, China Tel: 86-21-50968308 Fax: 86-21-50968310

E-mail: market@way-on.com Http://www.way-on.com



LP-MSM075/33

Surface mount fuses

Features

- □ Small size of 1812
- □ Normal working temperature with -40°C~85°C
- □ Lead-free and compliant with the European Union RoHS Directive 2011/65/EU
- ☐ Fast tripping resettable circuit protection
- □ Surface mount packaging for automated assembly





Product Dimensions (mm)

Part number	Α	В	С	D	Е	
	Max.	Max.	Max.	Min.	Min.	
LP-MSM075/33	4.73	3.41	1.30	0.30	0.30	



Electrical Characteristics									
Part number	I _H	Ι _Τ	V_{max}	I _{max}	T _{trip}	0	Pd _{typ}	R_{min}	R _{1max}
	(A)	(A)	(V)	(A)	Current(A)	Time(S)	(W)	(Ω)	(Ω)
LP-MSM075/33	0.75	1.50	33	40	8.0	0.20	1.0	0.10	0.48

I_H=Hold current: maximum current at which the device will not trip at 25 °C still air.

I_T=Trip current: minimum current at which the device will always trip at 25 ℃ still air.

V_{max}=Maximum voltage device can withstand without damage at rated current.

I_{max}=Maximum fault current device can withstand without damage at rated voltage.

T_{trip}=Maximum time to trip(s) at assigned current.

Pd_{typ}=Typical power dissipation: typical amount of power dissipated by the device when in state air environment.

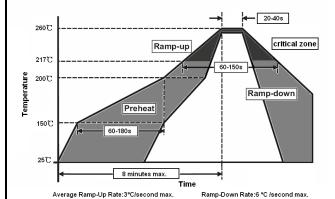
R_{min}=Minimum device resistance at 25 °C prior to tripping.

 $R_{1\text{max}}$ =Maximum device resistance measured in the nontripped state 1 hour post reflow.

Thermal Derating										
LP-MSM075/33	Maximum ambient operating temperature(℃)									
	-40	-20	0	20	25	40	50	60	70	80
Hold Current (A)	1.12	1.02	0.89	0.79	0.75	0.66	0.58	0.53	0.47	0.39
Trip Current (A)	2.24	2.04	1.78	1.58	1.50	1.32	1.16	1.06	0.94	0.78

Solder Reflow Recommendations





Solder Pad Layouts Part number A B C (mm) (mm) (mm) LP-MSM075/33 3.45 1.78 3.15

- * Recommended reflow methods: IR, Vapor phase, hot air oven.
- * Devices can be cleaned using standard industry methods and solvents.

Notes:

- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.
- Devices are not designed to be wave soldered to the bottom side of the board.

Package Information

Tape & Reel: 1000pcs per reel.

Effectivity: Reference documents shall be the issue in effect on the date of invitation for bid.

Caution: Operation beyond the rated voltage or current may result in rupture electrical arcing or flame.

Specifications are subject to change without notice.